



Fiscal Year 2017 First Half

# Business Report

January 1, 2017 to June 30, 2017



BIG IDEAS  
FOR EVERY SPACE

**Renesas Electronics Corporation**

Securities Code: 6723



Greetings

**I would like to express my sincere appreciation to our shareholders for their continued support and offer my greetings as we deliver the Business Report for the first half of fiscal year 2017.**

**A report on the overview of our business in the first half of the current fiscal year is presented below.**

Bunsei Kure

Representative Director, President and CEO

### **Results for the First Half of Fiscal Year 2017 and Consolidated Forecasts for the Next Quarter**

Consolidated net sales of Renesas Electronics Corporation for the first half of the current fiscal year were 375.8 billion yen, an increase of 17.5% year on year. Despite the continuing strong yen, the main contributing factors for the increase were the inclusion in the consolidated results of net sales of the US analog semiconductor supplier Intersil Corporation (“Intersil”) of which acquisition was completed in February 2017, dissipation of the impact from the 2016 Kumamoto Earthquake that occurred in the same period a year ago, and strong growth mainly in the automotive and industrial businesses.

Consolidated operating income for the first half of the current fiscal year was 44.3 billion yen, an improvement of 10.0 billion yen year on year. This was mainly due to an increase in net sales, which led the operating margin to reach 11.8%. Net income attributable to shareholders of parent company was 47.0 billion yen, an increase of 26.8 billion yen year on year, partly due to an insurance income associated with disasters.

Regarding financial forecasts, Renesas Electronics reports its consolidated forecasts on a quarterly basis because of the difficulty of forecasting full-year results with high accuracy due to the short-term volatility of the semiconductor market in which the Renesas Electronics Group (the “Group”) belongs. For the nine months ending September 30, 2017, we forecast net sales of 571.0 billion yen, an increase of 98.6 billion yen year on year. Operating income forecast is 65.0 billion yen, up 16.2 billion yen year on year. We have continuously improved our operating margin through increased sales and cost control, and expect to maintain an operating margin of 10% or higher for the nine months ending September 30, 2017.

Allocation of the acquisition costs for Intersil, which Renesas acquired in February 2017, has not been completed at the end of the second quarter ended June 30, 2017. The foregoing consolidated forecasts have been provisionally calculated based on the available information. Consolidated results for the nine months ending September 30, 2017 are subject to change as a result of the completion of the allocation of the acquisition costs of Intersil.

## Apology for Not Paying Dividends

Although the Group recorded consolidated net income (net income attributable to shareholders of parent company) as of the end of the first half of the current fiscal year, we will unfortunately not be paying an interim dividend. I offer my deepest apologies for not being able to live up to the expectations of our shareholders.

We will divert our retained earnings for strategic investment opportunities that will enable us to respond to rapid environmental changes to thrive in the global marketplace, and will aim to increase shareholder returns by improving corporate value. Based on a long-term standpoint, we aim to realize stable and sustained growth in profits to allow dividends to be reinstated. Payment of the year-end dividend is not determined at this point of time.

## Growth as One Global Renesas

We have completed the structural reforms that started in October 2013, and are now aiming to be the world's No. 1 in all of our segments by concentrating management resources in key segments, while at the same time reaping the results of the reform.

In the first half of the current fiscal year, based on the business integration associated with the completion of Intersil acquisition, we have transitioned our main businesses to the three business units that consist of "Automotive," "Industrial," and "Broad-based" and expanded the scope of responsibility for each of them from sales and marketing through to design and development. Also, in order to strengthen our stable supply system, we newly established the Supply Chain Management Unit to realize consistent SCM (Supply Chain Management) covering production to procurement.

Through these new business structures, we are aiming to move beyond our conventional Japan-centric

business management with the goal of becoming "One Global Renesas", a global organization that is not bound by region, and are conducting business operation to secure future growth.

In addition to launching these new structures, during the first half of the current fiscal year, there were two major events that are bound to become springboards for our steady growth trajectory.

One is our large company exhibition Renesas DevCon Japan 2017 held in April and the other is the secondary offering of Renesas Electronics' shares held by major shareholders in June.

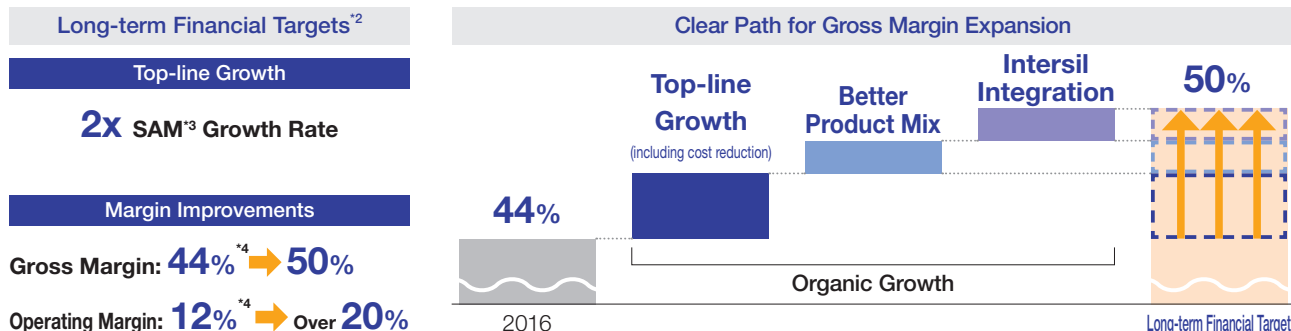
At Renesas DevCon Japan 2017, we introduced our leading-edge initiatives in autonomous driving and AI to approximately 2,000 visitors, the largest number of visitors thus far. The visitors mainly consisted of our customers and partners, which placed high expectations for our solutions.

In the secondary offering of Renesas Electronics' shares, we sold approximately 420 million shares to Japanese and international investors, equivalent to about 25% of approximately 1.67 billion shares issued and outstanding. As a result, our substantial liquidity ratio has increased from 3% to just under 30%, leading to improved liquidity. We believe that we have taken a new step forward as a global semiconductor company.

We will devote ourselves wholeheartedly to achieving the No.1 position in key segments within the fiercely competitive global environment, aiming to achieve semiconductor sales growth twice that of the growth rate of our targeting markets, a 50% gross margin, and a 20% or better operating margin. We will continue to make further efforts based on these initiatives taken in the first half of the current fiscal year, and I look forward to your continued support and understanding as we move forward with these efforts.

## New Long-term Financial Targets

In the fiscal year ended March 31, 2016, the Group completed the structural reforms that started in October 2013. The Group is now moving to a growth stage by reaping the results of these reforms and making a strategic and ongoing focused investment in its focus businesses. In November 2016, the Group updated its financial indicators, stating targets of a gross margin of 50% and an operating margin of over 20%. These targets will be achieved by 1) Top-line growth exceeding twice the market growth rate, 2) Better product mix, 3) PMI<sup>\*1</sup> with Intersil of which acquisition was completed in February 2017.



<sup>\*1</sup>: Post Merger Integration, which refers to the integration process after M&As.

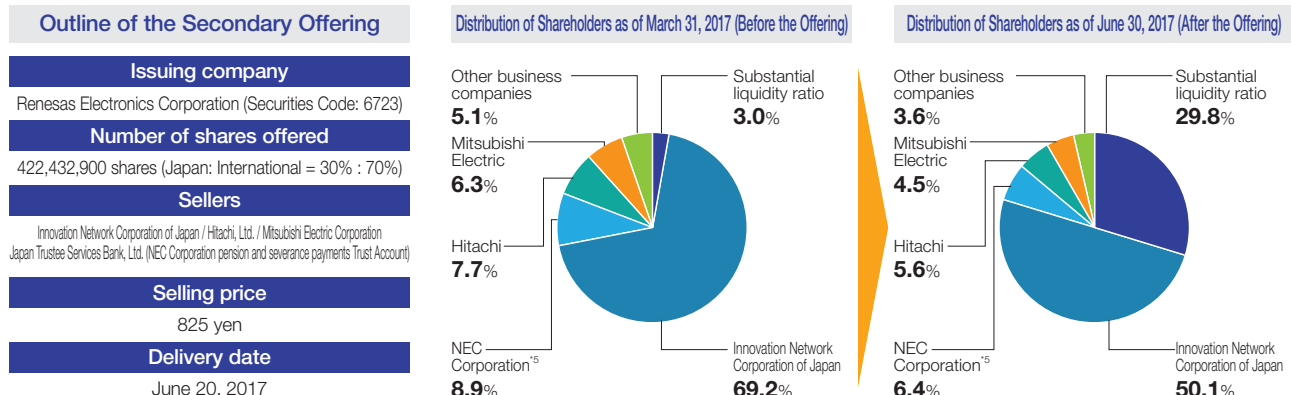
<sup>\*2</sup>: Long-term targets reflect non-GAAP adjustments to exclude amortization of goodwill and intangible assets, non-cash expenses such as stock compensation expenses and one-time expenses.

<sup>\*3</sup>: Served Available Market comprises of total semiconductor market excluding DRAM, flash memory, microprocessors and non-optical sensors.

<sup>\*4</sup>: Calculated on a calendar-year basis (Jan-Dec 2016) by adding FY2016/3 Q4 (3 months) and FY2016/12 (9 months) results based on non-GAAP basis.

## Improvement of Stock Liquidity

In June 2017, the Group completed the secondary offering of approximately 420 million shares to Japanese and international investors, equivalent to about 25% of approximately 1.67 billion shares issued and outstanding. As a result, the substantial liquidity ratio has increased to just under 30%, leading to improved liquidity. The Group believes that it has taken a new step forward as a global semiconductor company.



<sup>\*5</sup>: Includes shares held by Japan Trustee Services Bank held as NEC's pension and severance payments Trust Account.

## Aiming for Top-line Growth

The Group has designated “Automotive,” “Industrial,” and “Broad-based” as areas where it possesses strong technologies and products and where stable and high growth can be expected in the future. For these three areas, the Group will also combine Intersil’s products to provide devices, kits, and platforms as semiconductor solutions, aiming for top-line growth.

	AUTOMOTIVE	INDUSTRIAL	BROAD-BASED
			
<b>Platform Value</b>	Autonomous driving Integrated cockpit (Car navigation + ADAS)  <b>Renesas R-Car</b> Ecosystem <b>intersil</b> + LDD (Head-up display) + VSP (Display network)	Industrial ethernet EtherCAT CC-Link IE EtherNet/IP Industry-standard platform for Smart Factory + <b>intersil</b> PMIC + e-AI	<b>RENESAS synergy™</b>  IoT platform + Qualified software package + Ecosystem + <b>intersil</b> PMIC
<b>Kit Value</b>	EV motor ECU MCU + IGBT <b>RENESAS RH850</b>  Battery for xEV <b>RENESAS</b> + <b>intersil</b> BMIC/PMIC	 MCU + power semi + <b>intersil</b> PMIC for Smart Home Metering MCU + comm. ASSP SoC + <b>intersil</b> PMIC NW memory + <b>intersil</b> POL for Smart Infrastructure	 (Battery) (OIS) MCU + ASSP + <b>intersil</b> PMIC for broad-based applications
<b>Device Value</b>	Driving Steering Braking  MCU, analog, PMIC, power semi for Automotive	 MCU, SoC / ASSP, analog, PMIC, power semi for Smart Factory, Smart Home, Smart Infrastructure	 General-purpose MCU, analog, PMIC, power semi for broad-based applications

LDD: Laser Diode Driver VSP: Video Signal Processor MCU: Microcontroller Unit BMIC: Battery Management IC PMIC: Power Management IC  
e-AI: embedded Artificial Intelligence POL: Point of Load OIS: Optical Image Stabilizer

## Maximizing Shareholders Value

Free cash flows are created stably in accordance with continuous profit growth. In its efforts toward maximizing shareholder value, the Group aims to optimize capital allocation by considering various options such as growth investment, balance sheet management, and shareholder returns, in accordance with circumstances.

Growth Investment	Balance Sheet Management	Shareholder Returns
<ul style="list-style-type: none"> <li>Disciplined capital investment</li> <li>Further M&amp;As</li> </ul>	<ul style="list-style-type: none"> <li>Optimal financial leverage</li> <li>ROE-conscious</li> </ul>	<ul style="list-style-type: none"> <li>Consideration of dividends</li> <li>Consideration of share buyback</li> </ul>

## Maximizing Shareholders Value

## Event



April

### Large company exhibition held in Tokyo

On April 11, the Group held a large company exhibition in Tokyo entitled "Renesas DevCon Japan 2017" for the second time since September 2014. This time, the Group held a keynote speech, seminars, workshops and panels introducing its technology and solutions, with the theme of BIG IDEAS FOR EVERY SPACE.

In the keynote speech, our executives discussed our vision and the role played by our semiconductors. As one of the "BIG IDEAS FOR GREAT CARS" we introduced new initiatives to improve fuel efficiency and safety, which are indispensable for the development of cars, as well as autonomous driving technology. With regard to "BIG IDEAS FOR SMART SOCIETY", as IoT<sup>\*1</sup> and AI spread throughout society, we introduced new initiatives in e-AI<sup>\*2</sup> at the endpoint, such as embedded devices and terminals located at the ends of the network.

There were over 2,000 visitors on the day of the event, mostly customers and partners, who experienced our advanced solutions, making the event a great success.



\*1: IoT: the Internet of Things

\*2: e-AI: Embedded Artificial Intelligence

## Industrial / Other general-purpose



April

### Collaboration with the SECOM Group on IoT security infrastructure

Renesas Electronics, SECOM CO., LTD. and SECOM Trust Systems Co., Ltd. made an announcement on April 11 regarding collaboration on the provision of services using IoT technology and the development of security infrastructure for securely linking IoT devices.

Rapid advancement has been seen in recent years for IoT technology that collects and utilizes information by connecting various endpoint devices such as sensors and cameras to the Internet. Because devices manufactured and sold through various channels will be connected, IoT security infrastructure is required to facilitate secure and reliable links between IoT devices

Information security  
technology

Embedded security  
technology



IoT authentication security infrastructure development

2017

January

February

Announcement of  
full-year results

March

Ordinary general  
meeting of shareholders

April

## Automotive



April

### Renesas autonomy™, the new concept for autonomous driving

Today, the automobile industry is entering a new era of change, including the three trends of rapidly developing green cars, autonomous driving, and connected cars, and the spread of new service-oriented cars through synchronized cloud communications. Against this backdrop, on April 11 the Group announced Renesas autonomy™, a new platform concept to respond to the demand for total solutions for robust autonomous driving including cloud service, sensing, and vehicle control.

As lineups of Renesas autonomy, the Group will partner with approximately 200 companies participating in the R-Car Consortium to provide solutions for automotive control and EV motor control based on the world's most advanced automotive MCU, autonomous driving solutions ranging from sensing to recognition and judgment, as well as communication gateways for realizing connected cars.

On April 6 in Tokyo, we conducted test driving with a demonstration of autonomous driving car which embodies Renesas autonomy for the press, and participants experienced Level 4<sup>3</sup> autonomous driving solutions. Based on the Ford Lincoln, this demo car was developed by our US solutions development division over a short term through collaboration with key partners and universities in North America's autonomous driving industry.

Renesas autonomy



Test drive of an autonomous driving demo car

## Industrial / Other general-purpose



April

### e-AI making endpoints intelligent

In order to realize a smart society, we have positioned e-AI, which implements artificial intelligence technology at IoT endpoints, as one of our focus technologies. The Group is working on solutions with e-AI installed on microcontrollers (MCUs) and microprocessors (MPUs).

On April 11, the Group announced that it will develop new features installing results obtained from deep learning in MCUs and MPUs for the first time in the industry, and will start offering its first e-AI solutions from June. By connecting an AI learning environment to the integrated development environment for MCUs and MPUs, this solution will realize a smart society that incorporates learning results in MCUs and MPUs, makes endpoint embedded devices intelligent, and improves the quality of life.

\*3: Level 4: Completely automated driving operation requiring no involvement such as steering by the driver.

# Management



May

## Transfer of partial business to Hitachi Maxell

A part of the businesses managed by Renesas Semiconductor Package & Test Solutions Co., Ltd., our production subsidiary, was transferred to Hitachi Maxell, Ltd. as of May 1. The businesses transferred include: the electronics engineering and manufacturing service of electronic control boards for use in various industrial equipment and other semiconductor manufacturing equipment; and development, manufacturing, and sale of image recognition systems. Although the above businesses continue to generate profit, they are not strategically aligned with the Group's business direction, which center around the design, development, manufacturing, and sale of semiconductor solutions. Accordingly, the Group has been searching for a partner capable of growing and generating synergy effects from these businesses. As a result, at the end of January 2017, we concluded a definitive agreement to transfer these businesses to Hitachi Maxell, which intends to utilize them to further expand its own businesses.

# Management



May to June

## Secondary offering of Renesas Electronics' shares

On May 18, the Group announced a secondary offering of approximately 420 million shares, which is equivalent to about 25% of approximately 1.67 billion shares issued and outstanding, and completed the offering to Japanese and international investors on June 20. Stocks offered included some of those owned by Innovation Network Corporation of Japan, NEC Corporation<sup>\*4</sup>, Hitachi, Ltd., and Mitsubishi Electric Corporation, decreasing for example the shareholding ratio of Innovation Network Corporation of Japan from 69.2% to 50.1%. Through this offering, the Group increased its substantial liquidity ratio to just under 30%, and diversified its shareholder base.

<sup>\*4</sup>: NEC Corporation: A portion of the holdings of Japan Trustee Services Bank, Ltd., a pension and severance payments Trust Account of the company, was also sold.

May

Announcement of first-quarter results

June

July

Announcement of second-quarter results

August

# Automotive



May

## Strategic collaboration with Great Wall Motors

Renesas Electronics and Great Wall Motors Co. Ltd., China's largest SUV and pickup manufacturer, made an announcement on May 25 regarding strategic collaboration on joint development of automotive semiconductor technologies and solutions in areas such as new energy vehicles<sup>\*5</sup> and autonomous driving cars in China. The top management of both companies attended the signing ceremony held in Baoding, China, where they confirmed that they would develop technologies in the fields of (1) key components of new energy vehicles, (2) automotive network systems capable of high-speed and robust communication, (3) next-generation automotive infotainment systems supporting safety and comfort, and (4) advanced driving assistance systems (ADAS) essential for autonomous driving. Both companies will incorporate state-of-the-art technologies into new energy vehicles and autonomous driving cars and will contribute to relevant market growth in China.



The signing ceremony was held with the attendance of Wei Jianjun, Chairman of Great Wall Motors (right) and Bunsei Kure, President and CEO of Renesas Electronics (left).

<sup>\*5</sup>: New energy vehicles: electric vehicles (EV), plug-in hybrid vehicles (PHEV), etc.

# Management



February and July

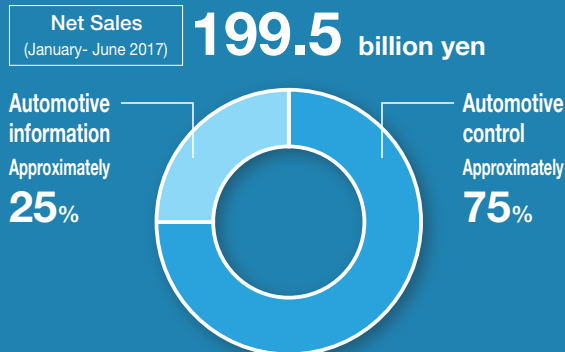
## Toward a global organization incorporating Intersil

On February 24, we completed acquisition of the US analog semiconductor supplier Intersil Corporation, and Necip Sayiner, their President, CEO and Director was appointed Executive Vice President of Renesas Electronics. Through the business integration with Intersil, we aim to move beyond our conventional Japan-centric business management with the goal of becoming a truly global company as "One Global Renesas", a global organization that is not bound by region. To this end, we started full-scale operation of the new organization from July 1. We transitioned our main businesses to three business units: the Automotive Solution Business Unit responsible for automobiles, the Industrial Solution Business Unit focused on application-specific solutions other than automobiles, such as industrial solutions, and the Broad-Based Solution Business Unit which focuses on a wide variety of end-market solutions and a broad set of customers for general purposes.

In each business unit, we will expand the range of responsibilities from sales and marketing through to design and development, and will enable rapid and consistent decision-making.



## Automotive



### ● Products

MCUs (microcontrollers), SoCs (system-on-chips), analog semiconductor devices, power semiconductor devices

### Categories

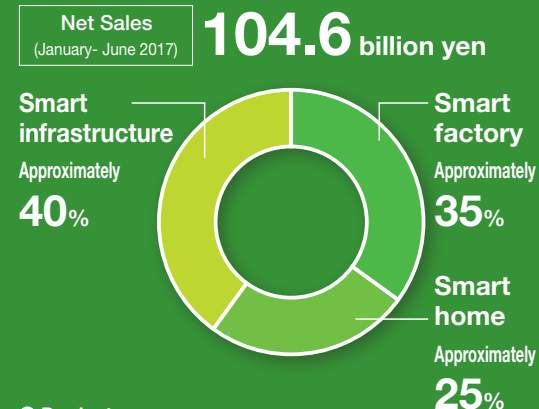
**Automotive control:** For controlling automobile engines and bodies, etc.

**Automotive information:** For automotive information systems such as navigation systems

### ■ Overview of Net Sales in the First Half

Net sales in the Automotive business for the first half of fiscal year 2017 were 199.5 billion yen, an increase of 14.4% year on year. Sales increased in both the “Automotive control” and “Automotive information” categories mainly due to expansion of the Automotive business and dissipation of the impact from the 2016 Kumamoto Earthquake that occurred in the same period a year ago.

## Industrial



### ● Products

MCUs (microcontrollers), SoCs (system-on-chips)

### Categories

**Smart factory:** For industrial equipment, etc.

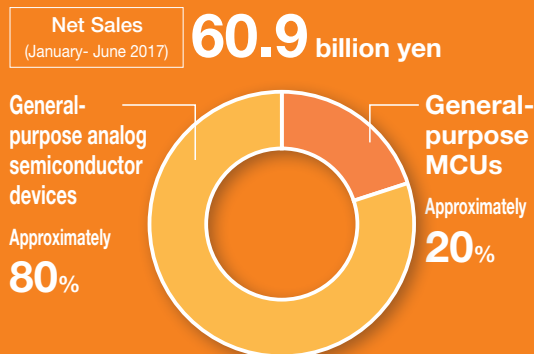
**Smart home:** For home appliances, etc.

**Smart infrastructure:** For office automation (OA) equipment and network infrastructure, etc.

### ■ Overview of Net Sales in the First Half

Net sales in the Industrial business for the first half of fiscal year 2017 were 104.6 billion yen, an increase of 10.5% year on year. Despite a decrease in sales in the “Smart infrastructure” category, Industrial business results increased overall mainly due to increased sales in both the “Smart factory” and “Smart home” categories driven by strong demand for industrial equipment, including FA (factory automation), and air conditioners in China.

## Broad-based



### ● Products

MCUs (microcontrollers), analog semiconductor devices

### Categories

Offering “General-purpose MCUs” and “General-purpose analog semiconductor devices” for a wide variety of end-market solutions

### Overview of Net Sales in the First Half

Net sales in the Broad-based business for the first half of fiscal year 2017 were 60.9 billion yen, an increase of 54.0% year on year. Sales increased in the “General-purpose analog semiconductor devices” category following the acquisition of Intersil, despite decreased sales in the “General-purpose MCUs” category.

### Consolidated Balance Sheets

	As of December 31, 2016	As of June 30, 2017
	Billion Yen	Billion Yen
Total assets	<b>823.1</b>	<b>994.2</b>
Net assets	<b>422.4</b>	<b>462.5</b>
Equity ratio (%)	<b>51.0</b>	<b>46.2</b>

### Consolidated Statements of Operations

	First Half of Prior Year (From January 1, 2016 to June 30, 2016)	First Half of Current Fiscal Year (From January 1, 2017 to June 30, 2017)
	Billion Yen	Billion Yen
Net sales	<b>319.8</b>	<b>375.8</b>
Sales from semiconductors	<b>310.7</b>	<b>366.9</b>
Sales from others	<b>9.0</b>	<b>8.9</b>
Operating income	<b>34.3</b>	<b>44.3</b>
Ordinary income	<b>27.5</b>	<b>43.2</b>
Net income attributable to shareholders of parent company	<b>20.3</b>	<b>47.0</b>
	Yen	Yen
Exchange rate (USD)	<b>115</b>	<b>112</b>
Exchange rate (Euro)	<b>127</b>	<b>122</b>

### Consolidated Statements of Cash Flows

	First Half of Prior Year (From January 1, 2016 to June 30, 2016)	First Half of Current Fiscal Year (From January 1, 2017 to June 30, 2017)
	Billion Yen	Billion Yen
Net cash provided by (used in) operating activities	<b>44.6</b>	<b>69.2</b>
Net cash provided by (used in) investing activities	<b>(15.2)</b>	<b>(375.4)</b>
Free cash flows	<b>29.4</b>	<b>(306.2)</b>

(Note) Amounts are rounded to the nearest 100 million yen. Renesas Electronics Group implemented a change of the fiscal term in which the fiscal year-end changed from March 31 to December 31, starting from fiscal year 2016. As a result, the previous consolidated fiscal year, in which the change in fiscal year-end took place, comprised the nine months from April 1, 2016 to December 31, 2016, and the consolidated results for the first half of fiscal year 2017 are compared with the corresponding period of the previous year (January 1, 2016 to June 30, 2016).

## Corporate Outline

### Company Name

Renesas Electronics Corporation

### Established

November 1, 2002

(Commenced operations under the name of Renesas Electronics Corporation on April 1, 2010)

### Capital Stock

10 billion yen

### Major Operations

Research, development, design, manufacture, sale, and servicing of semiconductor products

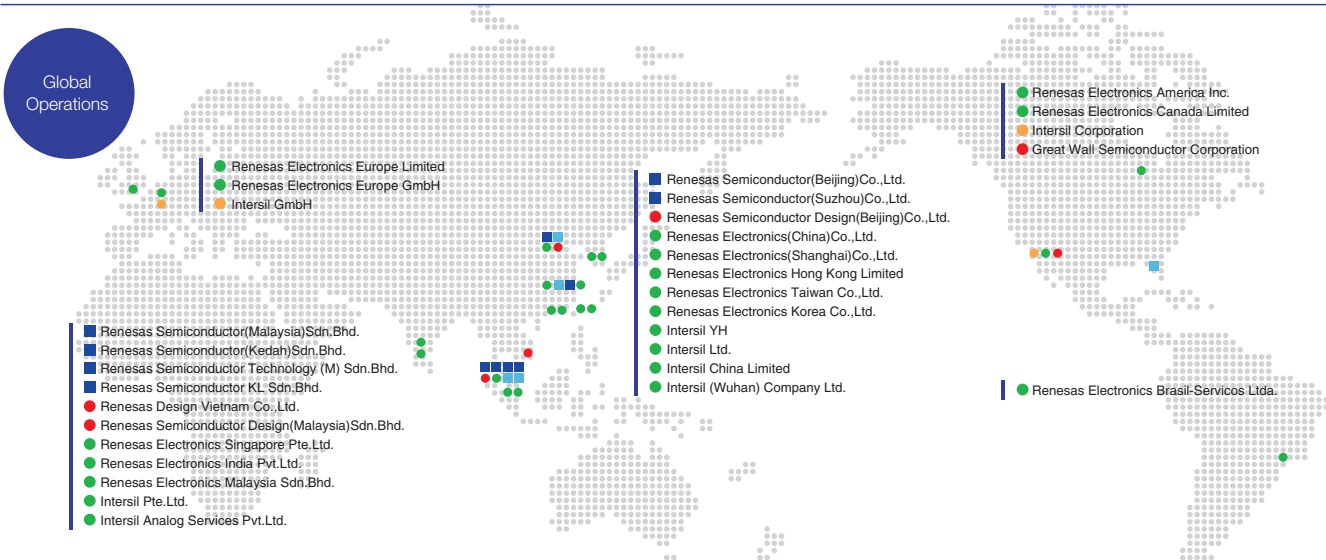
### Employees (Consolidated)

20,138 (As of June 30, 2017)

### Headquarters Location

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo, Japan

## Global Network (As of July 1, 2017)



## Executives (As of July 1, 2017)

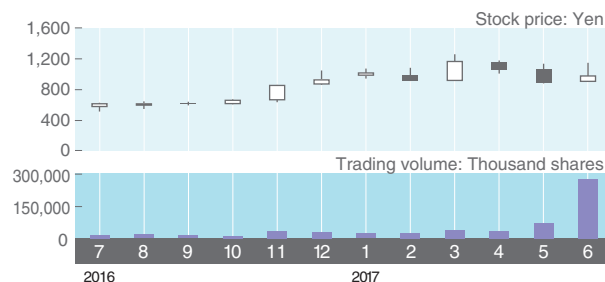
Representative Director, Chairman  
Representative Director, President and CEO  
Outside Director  
Outside Director  
Outside Director  
Outside Corporate Auditor  
Outside Corporate Auditor (part-time)  
Outside Corporate Auditor (part-time)  
Outside Corporate Auditor (part-time)  
Executive Vice President and CFO  
Executive Vice President  
Executive Vice President  
Executive Vice President  
Executive Vice President  
Executive Vice President of Renesas Electronics Corporation and President, CEO and Director of Intersil Corporation, and President of Renesas Electronics America  
Senior Vice President of Renesas Electronics Corporation and President of Renesas Electronics Europe  
Senior Vice President and CTO  
Senior Vice President and Chairman of Renesas Electronics (China)  
Senior Vice President  
Senior Vice President  
Senior Vice President

Tetsuya Tsurumaru  
Bunsei Kure  
Tetsuro Toyoda  
Kenichi Hattori  
Jiro Iwasaki  
Kazuki Fukuda  
Yoshinobu Shimizu  
Kazuyoshi Yamazaki  
Takeshi Sekine  
Hidetoshi Shibata  
Yoshikazu Yokota  
Ryuji Omura  
Masahiko Nozaki  
Manabu Kawashima  
Necip Sayiner  
Michael Hannawald  
Hideto Hidaka  
Tomomitsu Maoka  
Hirotaka Yamanami  
Hiroto Nitta  
Shinichi Yoshioka

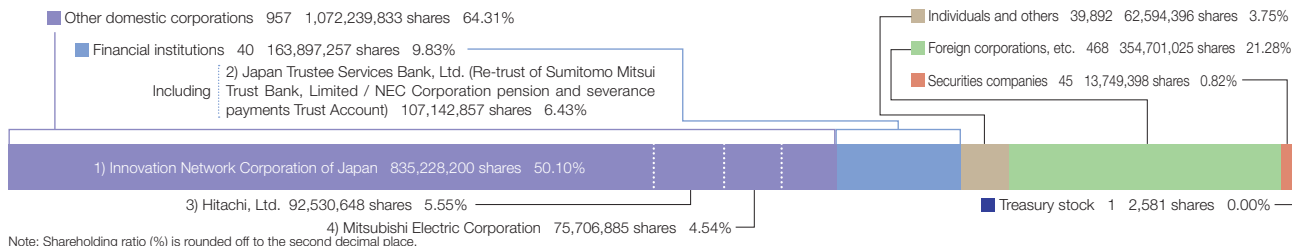
## Status of Stock

Total Number of Authorized Shares	3,400,000,000
Total Number of Issued Shares	1,667,184,490
Number of Shareholders	41,403

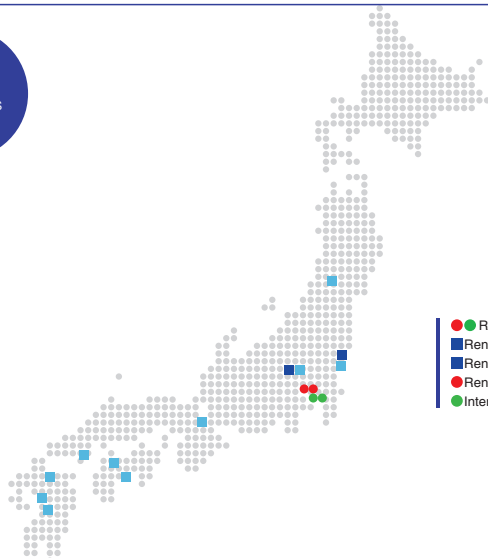
## Stock Price Chart (From July 1, 2016 to June 30, 2017)



## Distribution of Shareholders and Shares



Domestic Operations



- Renesas Electronics Corporation
- Renesas Semiconductor Manufacturing Co., Ltd.
- Renesas Semiconductor Package & Test Solutions Co., Ltd.
- Renesas Engineering Services Co., Ltd.
- Intersil Corporation

- Manufacturing/Manufacturing Sup
- Factories
- Design, development, application technologies
- Sales
- Operating companies

## ■ Shareholders' Memo

<b>Fiscal Year</b>	January 1 to December 31
<b>Ordinary General Meeting of Shareholders</b>	Within three months after ending every business year
<b>Date of Record</b>	Ordinary General Meeting of Shareholders: December 31 Dividends: (Year-end) December 31 (Interim) June 30
<b>Minimum Trading Units</b>	100 shares
<b>Transfer Agent and Special Account Management Institution</b>	Sumitomo Mitsui Trust Bank, Limited 1-4-1 Marunouchi, Chiyoda-ku, Tokyo
<b>Transfer Agent Place of Business</b>	Stock Transfer Agency Business Department, Sumitomo Mitsui Trust Bank, Limited 1-4-1 Marunouchi, Chiyoda-ku, Tokyo
<b>Mailing Address</b>	Stock Transfer Agency Business Department, Sumitomo Mitsui Trust Bank, Limited 2-8-4 Izumi, Suginami-ku, Tokyo 168-0063, Japan
<b>Website URL</b>	<a href="http://www.smtb.jp/personal/agency/index.html">http://www.smtb.jp/personal/agency/index.html</a>
<b>Stock Exchange Listing</b>	Tokyo Stock Exchange

## [Special Accounts]

Accounts (“special accounts”) have been opened at the above-mentioned Sumitomo Mitsui Trust Bank, Limited, which is the transfer agent, for shareholders who had not used the Japan Securities Depository Center, Incorporated prior to the computerization of share certificates.

### Our IR Website

Our Investor Relations (IR) website is designed to allow easy navigation and easy access to various information materials in order for shareholders to gain a better understanding of the Group.

In addition, the “Renesas at a Glance” section provides information for individual investors including a message from the CEO, overview of our business, IR and stock information, and an introduction to basic knowledge about semiconductors.

Please take a look.

Investor Relations website:

<https://www.renesas.com/en-hq/about/ir>



### Renesas Electronics Corporation

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

Telephone: +81-3-6773-3000